

Amendments to the Specification:

Please replace paragraph [0065] of the published application with the following rewritten paragraph:

Moreover, the notch 20 is formed on the periphery of the support column 15 on the inner circumferential surface of the ring-like plate 13. The notch 20 is composed of a semi-circular an approximately circular or approximately semi-circular fitting portion portion 20a as a hole into which the support column 15 is fitted, and an opening 20b which opens the fitting portion portion 20a to the inner circumferential direction of the ring-like plate 13. When the opening 20 is viewed from the above and the wafer support portion 16 is projected on the opening 20b in a state where the support column 15 is fitted to the fitting portion 20a, it is preferable that the opening 20b be housed is housed in the center of the opening 20b, and that an open width of the opening 20b be larger is larger than the width of the wafer support portion 16. When the opening 20b which opens in the inner circumferential direction of the ring-like plate 13 is provided on the notch 20 as described above, the gas which has hit on the wafer support portion 16 from the above goes around both sides of the wafer support portion 16, and directly flows downward through the opening portion 20b. Accordingly, turbulence becomes difficult to occur on the wafer support portion 16. Hence, a difference in flow of the processing gas is eliminated between a portion having the support column 15 with the wafer support portion and the other portion. In particular, as in the illustrated example, it is preferable that the opening 20b open in a fan shape to the inner circumferential surface side. This is because, when the opening 20 opens in the fan shape, the turbulence becomes more difficult to occur on the wafer support portion 16, and the difference in flow of the processing is eliminated more between the portion having the support column 15 with the wafer support portion and the other portion.

Please replace paragraph [0066] of the published application with the following rewritten paragraph:

Moreover, as shown in FIG. 5, a tip of the wafer support portion 16 formed into the columnar shape should be rounded (R) or chamfered (C). Moreover, with regard to a fixing angle of the columnar wafer support portion 16 to the support column 15, each wafer support portion 16 may be provided parallel to the wafer 200 as shown in FIG. 5, or each wafer support portion 16 may be fixed to the support column 15 so as to be inclined downward by θ , as shown in Fig. 6.

Please replace paragraph [0079] with the following rewritten paragraph:

Note that, though the description has ~~been made~~ of the case where the processing gas flows in the direction from the wafers 200 to the ring-like plates 13 when the processing gas flows across the inner tube in FIG. 8, the above description can also be applied to the case where the processing gas flows in a direction from the ring-like plates 13 to the wafers, and to the case where the processing gas flows upward from the bottom.